

Elite Material Co., Ltd.

Global leading provider of eco-friendly laminates

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Market position of the company

Global No. 1 provider of:

- Halogen-free laminates
- Laminates for HDI (high-density interconnect) PCB
- Laminates for smartphones

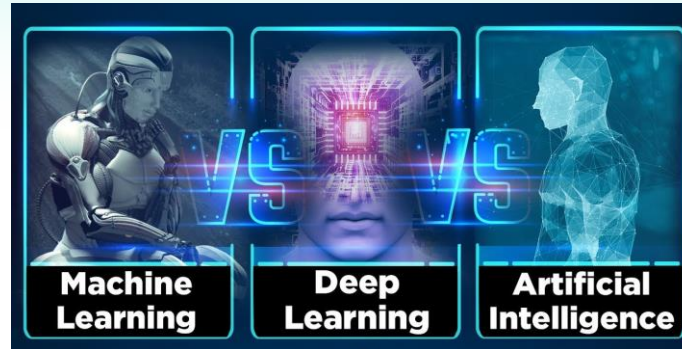


HDI growth remains on the upward trend

- Proliferation of HDI PCB applications
- Material upgrade raises the laminate dollar content per square inch



Proliferation of HDI PCB applications



Smartphones



SSD & Memory modules



Ultra thin Laptops & tablets



Gaming



AR/VR



Smart Speakers



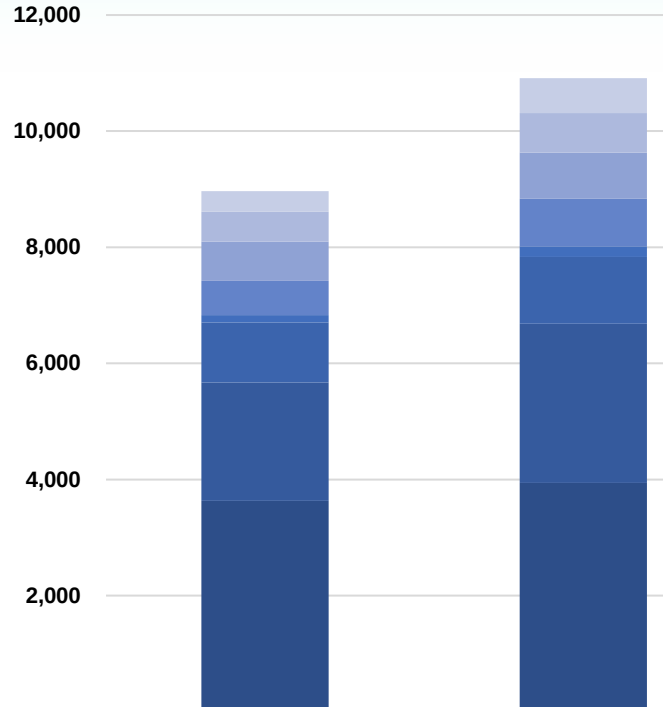
Drones



Wearables

Multiple factors drive the growth of HDI

Unit: US\$ million

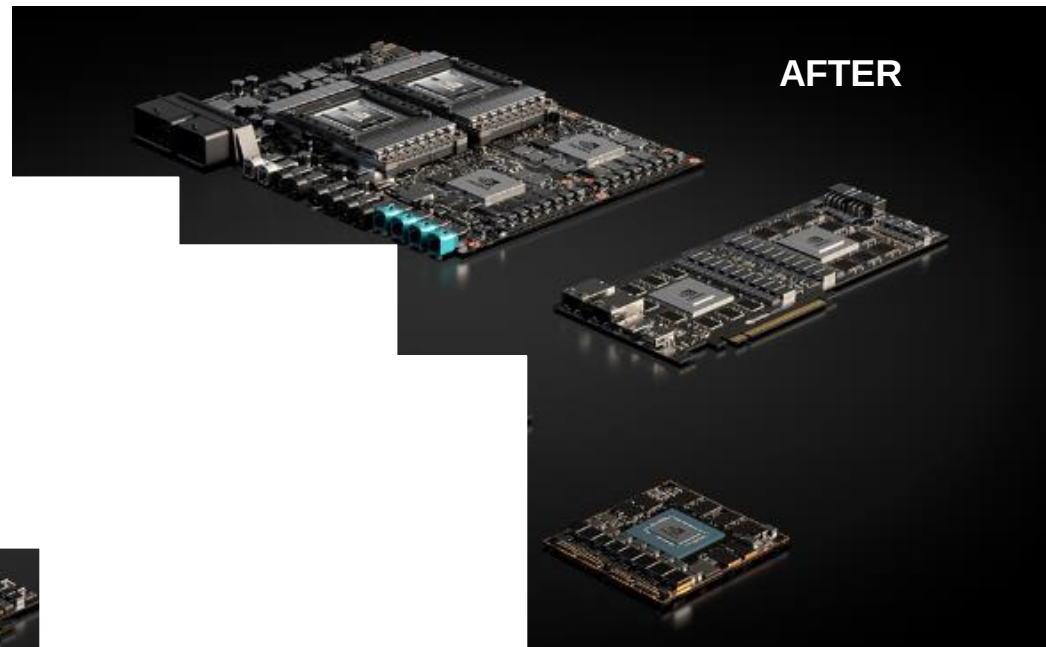
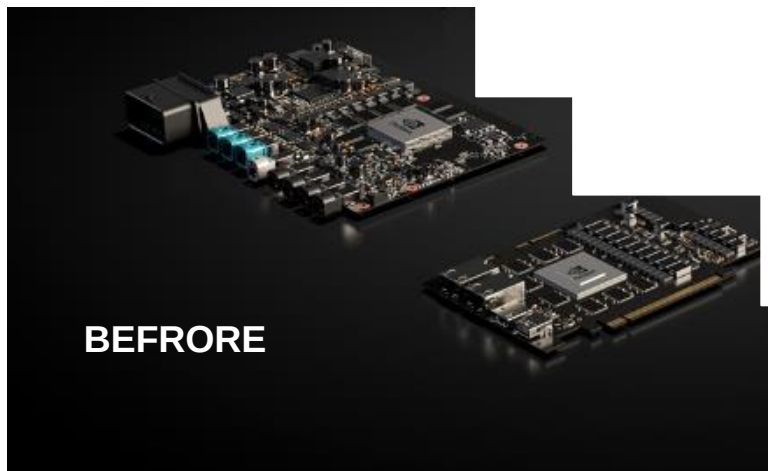


	2017	2022F
Others (Module, SiP, Wearables, etc.)	357	603
Automotive	515	683
Datacom and Telecom Infrastructure	678	794
Portable Consumer	587	816
DRAM & SSD	126	183
Tablet, NB and PC	1,034	1,154
Mobile Phones - Anylayer	2,042	2,739
Mobile Phones - HDI regular	3,629	3,942

- CAGR of overall HDI growth is forecast to be 4.0% from 2017 to 2022.
- Any-layer HDI consumed by mobile phones is predicted to have a CAGR of 6.05% during the forecast period.
 - Implication: Laminate \$ content rises, though the total number of smartphone units is considered to be stagnant.
- SSD & DRAM would have the highest CAGR of 7.75%.
 - Implication 1: the decline in NAND Flash price, and in turn lowering the SSD price, accelerates the adoption rate of SSD.
 - Implication 2: Heterogeneous integration of semiconductor, such as SSD +MLC/TLC, requires finer pinch; therefore, HDI design is preferred.
- Increasing electronic content of automotive vehicles, e.g. ADAS, telematics, and infotainment systems, leads to HDI growth, projected to have a CAGR of 5.81%.
- PCBs in datacom & telecom infrastructure, and portable consumers, e.g. AR/VR, also begin to adopt HDI design.

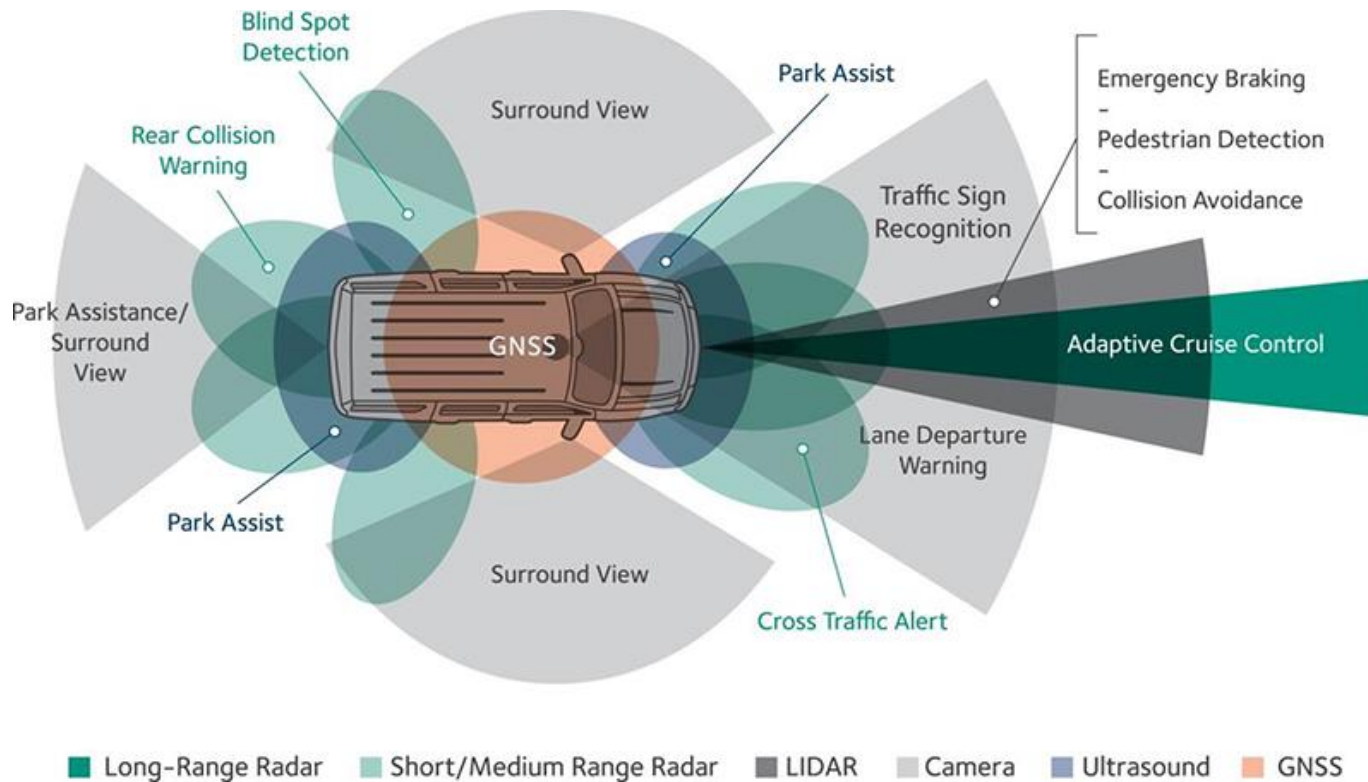
PCB design of networking hardware is migrating

- **Trend 1: Halogen-free laminates are preferred or even becoming requested.**
 - New platforms of PCIe4 include, but are not limited to, Intel's Whitely, request only halogen-free laminates.
- **Trend 2: AI semiconductors, newly-developed GPUs, heterogeneous integration of semiconductors, and double-die package with a plurality of single chip increases pin counts substantially.**
 - Fine line/pinch architecture design by PCB constructors is strongly preferred or a must.



Source: nVidia

Increasing electronic content per car



■ Autonomous and Safety

- Radar
- Camera / Vision system
- In-vehicle server / AI Module
- Chassis and safety ECUs
- Active sensing ECUs

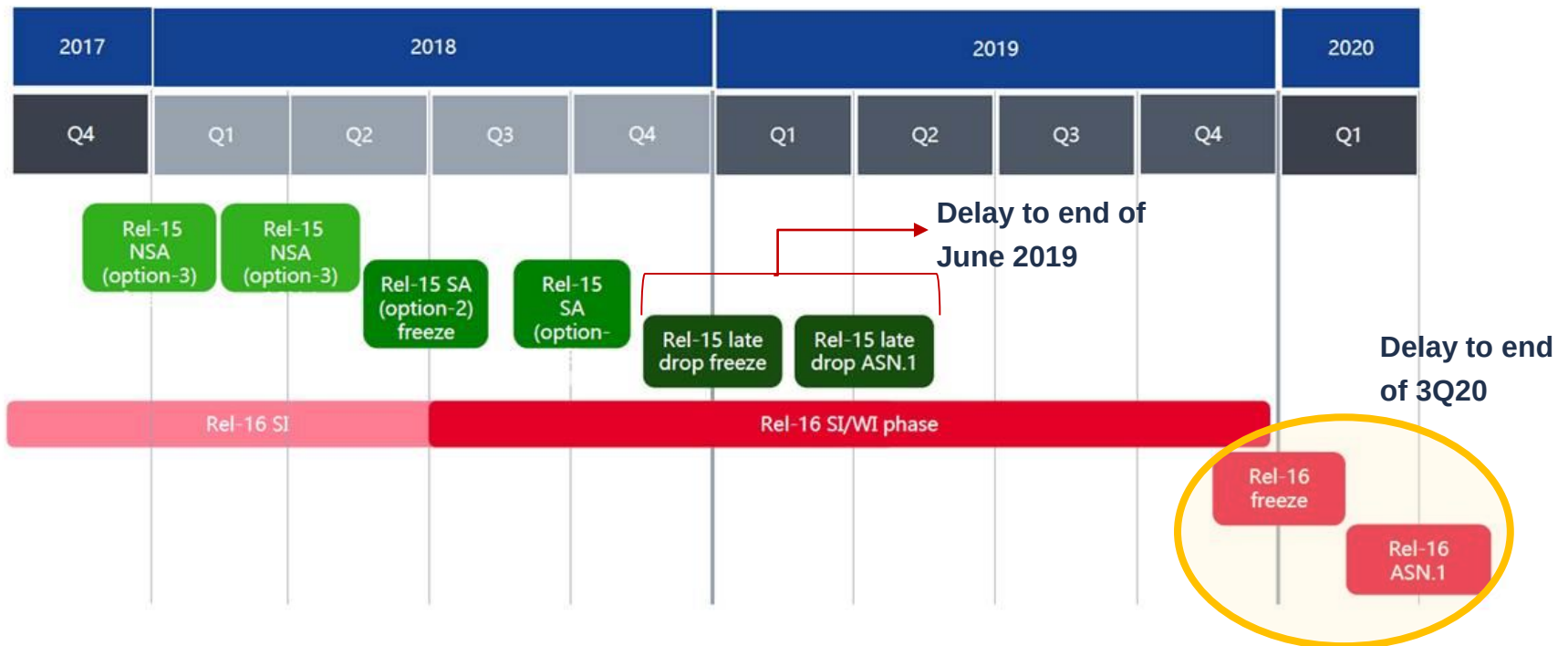
■ Connectivity and Infotainment

- V2X connection
- Central gateway
- Intelligent CarKey
- GNSS (Global Navigation Satellite System)
- Infotainment ECU / Module / e-Cockpit (WiFi, Bluetooth, Wireless access, Memory, Cellular, Navi)

Controversial opinion about the global 5G standard

- On 16th December 2018, Balazs Berftenyi, Chairman of 3GPP announced that the finalization of Release-15 late drop will be postponed for three months.

3GPP standardization timeline

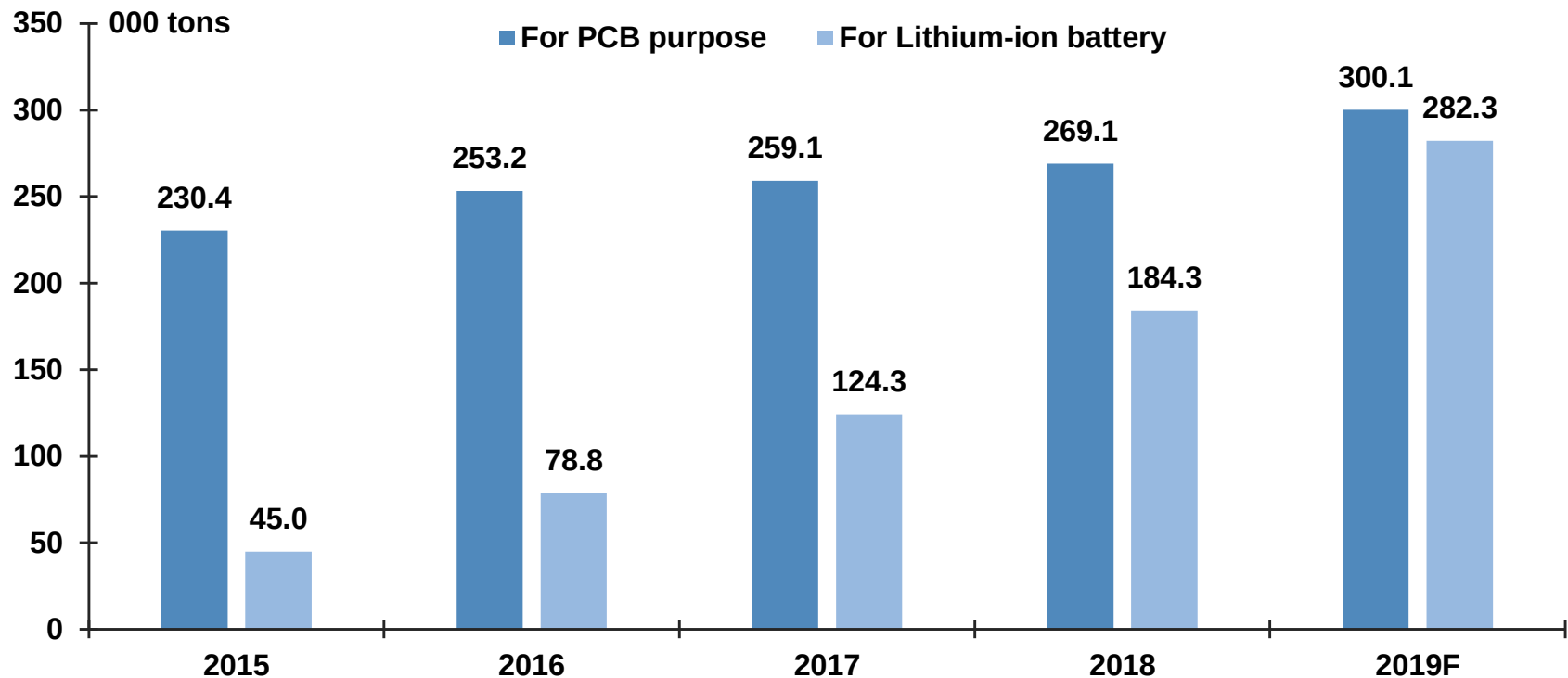


Source: 3GPP website; www.3gpp.org

Cost pressure is expected to be relieved

- Capacity of copper foils consumed by PCBs is forecast to increase by 11.5% YoY, from 269,100 tons in 2018 to 300,100 tons in 2019.
- Processing fee of copper foil manufacturers is expected to remain flat or even trend down.

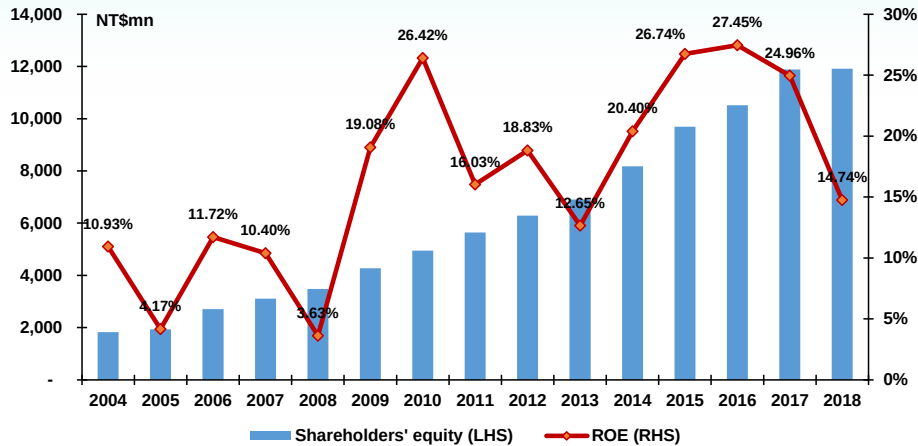
Capacity of copper foils



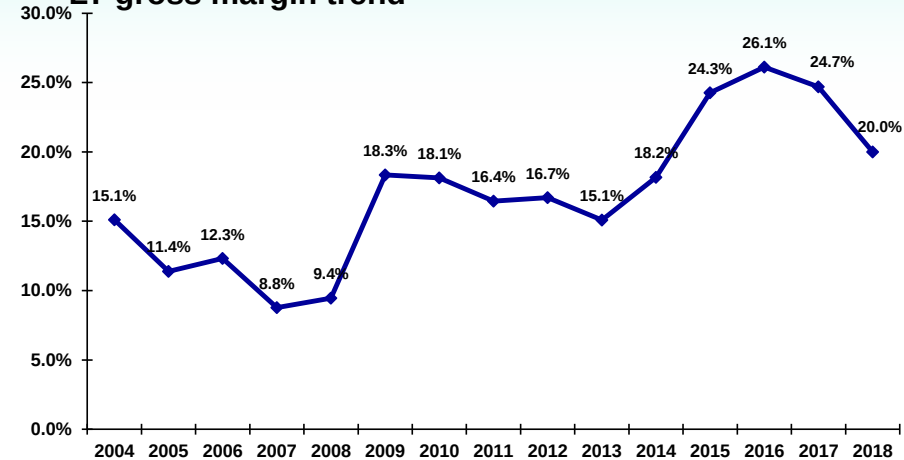
Source: TPCA (Taiwan Printed Circuit Association)

Operating and financial results

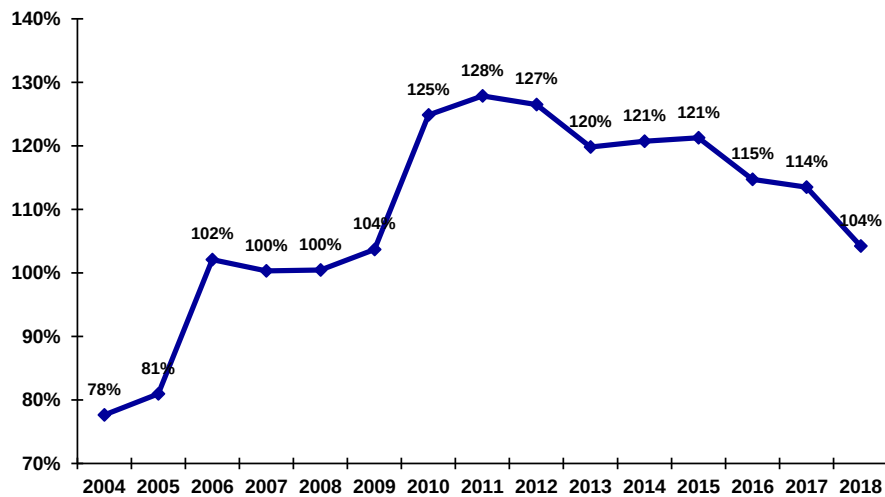
ROE trend



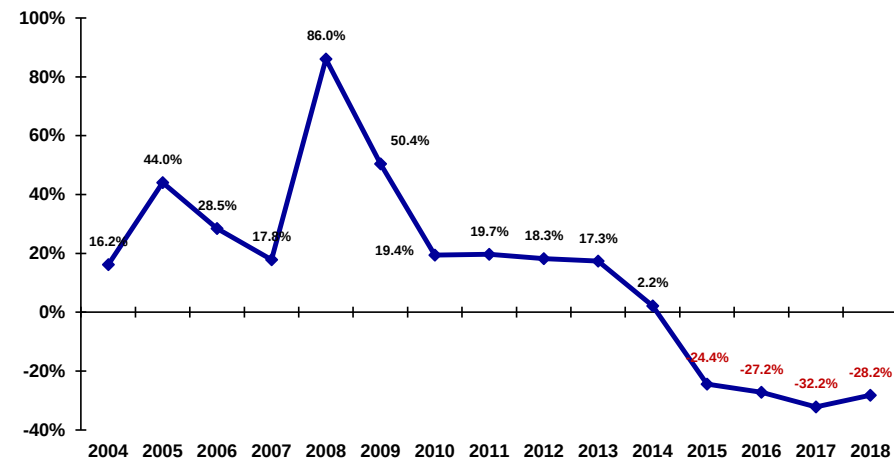
LT gross margin trend



Asset turnover ratio

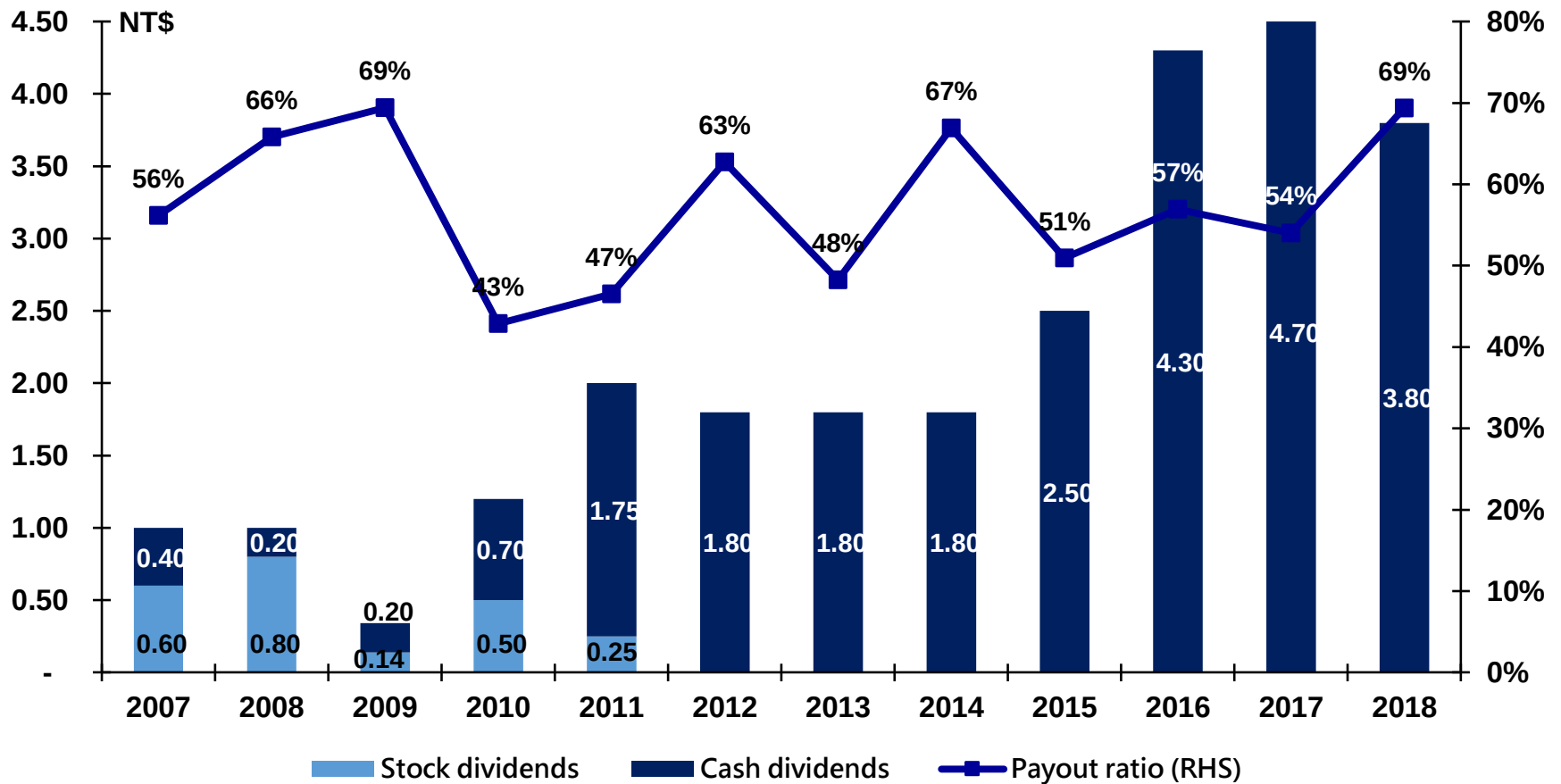


Net debt/equity ratio



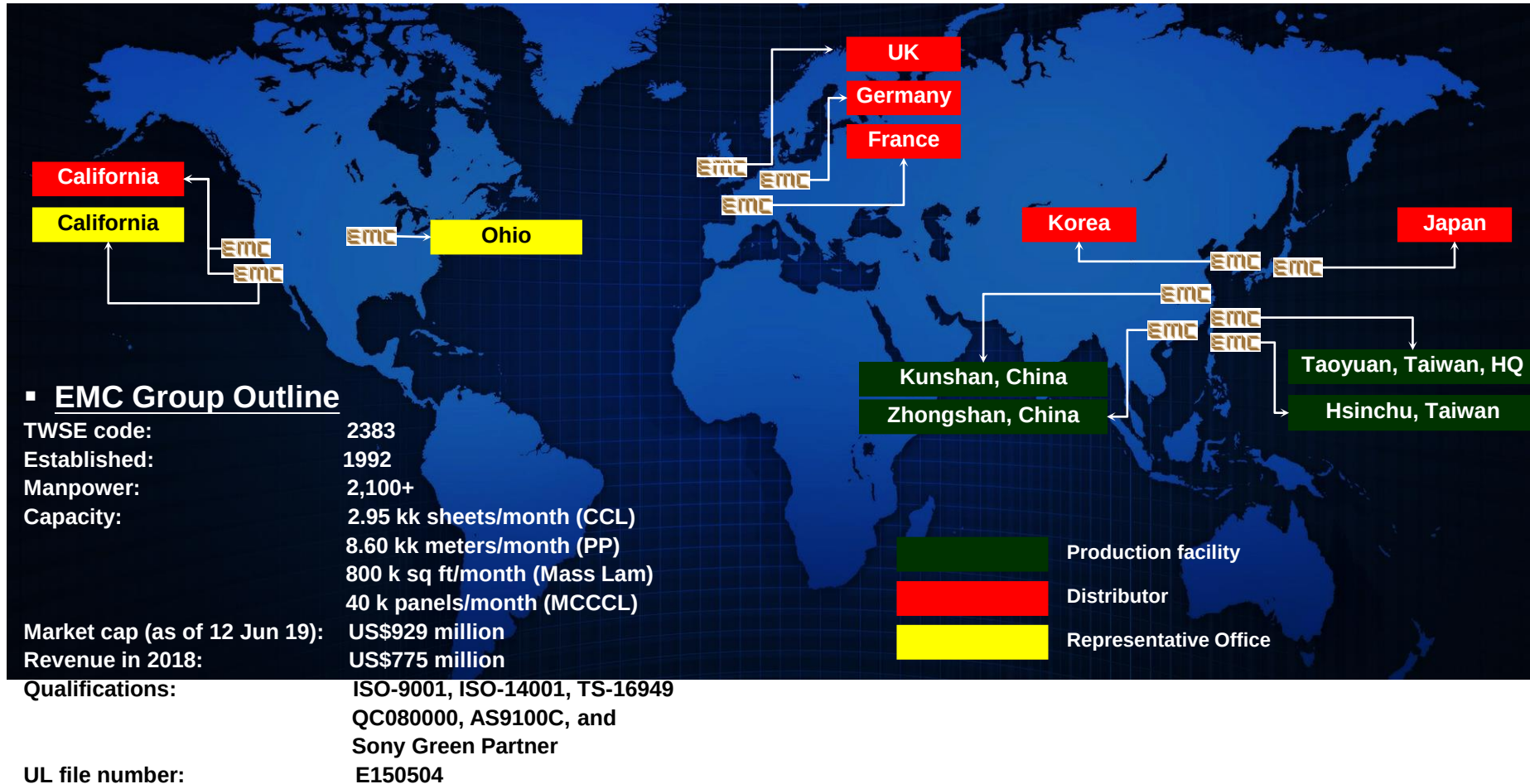
Note: Net debt = Interest-bearing debts – cash amount

Dividend payout history



APPENDIX

Company profile – global footprint



Production site and monthly capacity

Total capacity/month	
CCL	2,950 k sheets
PP	8,600 k meters
Mass Lam	800 k sq ft
MCCCL	40 k panels



EMC (KS) Kunshan	
CCL	1,350 k sheets
PP	3,300 k meters
Manpower	850+



EMC (TW) Taoyuan	
CCL	500 k sheets
PP	1,800 k meters
Manpower	500+



EMC (TW) Hsinchu	
CCL	150 k sheets
PP	1,400 k meters
Mass Lam	800 k sq ft
MCCCL	40 k panels
Manpower	250+



EMC (ZS) Zhongshan	
CCL	950 k sheets
PP	2,100 k meters
Manpower	600+

1Q19 P&L summary

Unit: NT\$ million

	1Q19	4Q18	QoQ	1Q18	YoY
Revenue	5,072	5,404	-6.1%	5,312	-4.5%
Gross profit	1,074	979	9.7%	1,002	7.1%
Operating profit	652	557	17.0%	562	15.9%
Interest income (expenses)	9	7	33.0%	6	59.2%
Other income (expenses)	18	43	-58.1%	(8)	na
Income before tax	679	607	11.9%	560	21.2%
Tax expenses	203	180	13.0%	284	-28.5%
Net income	476	427	11.4%	276	72.3%
EPS (NT\$) - basic	1.49	1.34	11.4%	0.86	72.3%
Gross margin (%)	21.2%	18.1%		18.9%	
Operating margin (%)	12.9%	10.3%		10.6%	
Net margin (%)	9.4%	7.9%		5.2%	

Five-year consolidated P&L summary

Unit: NT\$ million

	2014	2015	2016	2017	2018	1Q18	1Q19	YoY
Revenue	18,885	20,870	22,070	23,610	22,891	5,312	5,072	-4.5%
Gross profit	3,431	5,064	5,766	5,828	4,576	1,002	1,074	7.1%
Operating profit	1,598	3,249	3,939	4,007	2,755	562	652	15.9%
Interest income (expenses)	(47)	(36)	(27)	16	34	6	9	59.2%
Other income (expenses)	287	117	6	6	38	(8)	18	na
Income before tax	1,838	3,331	3,917	4,028	2,827	560	679	21.2%
Tax expenses	297	938	1,143	1,233	1,072	284	203	-28.5%
Net income	1,542	2,392	2,774	2,795	1,754	276	476	72.3%
EPS (NT\$) - basic	4.82	7.48	8.68	8.74	5.49	0.86	1.49	72.3%
Gross margin (%)	18.2%	24.3%	26.1%	24.7%	20.0%	18.9%	21.2%	
Operating margin (%)	8.5%	15.6%	17.8%	17.0%	12.0%	10.6%	12.9%	
Net margin (%)	8.2%	11.5%	12.6%	11.8%	7.7%	5.2%	9.4%	